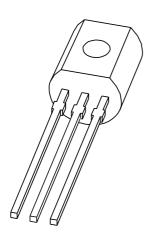
# DISCRETE SEMICONDUCTORS

# DATA SHEET



BC636; BC638; BC640 PNP medium power transistors

Product specification Supersedes data of 2001 Oct 10 2004 Oct 11





# **PNP** medium power transistors

BC636; BC638; BC640

#### **FEATURES**

- High current (max. 1 A)
- Low voltage (max. 80 V).

# **APPLICATIONS**

· Audio and video amplifiers.

#### **DESCRIPTION**

PNP medium power transistor in a TO-92; SOT54 plastic package. NPN complements: BC635, BC637 and BC639.

#### **PINNING**

PIN	DESCRIPTION
1	base
2	collector
3	emitter

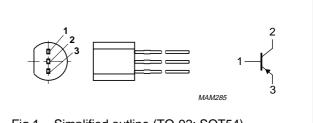


Fig.1 Simplified outline (TO-92; SOT54) and symbol.

#### **ORDERING INFORMATION**

TYPE NUMBER	PACKAGE					
I TPE NOMBER	NAME	DESCRIPTION	VERSION			
BC636	SC-43A	plastic single-ended leaded (through hole) package; 3 leads	SOT54			
BC638						
BC640						

# PNP medium power transistors

BC636; BC638; BC640

# **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter			
	BC636		_	<b>-45</b>	V
	BC638		_	-60	V
	BC640		_	-100	V
V <sub>CEO</sub>	collector-emitter voltage	open base			
	BC636		_	<b>-45</b>	V
	BC638		_	-60	V
	BC640		_	-80	V
V <sub>EBO</sub>	emitter-base voltage	open collector	_	<b>-</b> 5	٧
I <sub>C</sub>	collector current (DC)		_	<b>-1</b>	А
I <sub>CM</sub>	peak collector current		_	-1.5	А
I <sub>BM</sub>	peak base current		_	-200	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; note 1	_	0.83	W
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T <sub>amb</sub>	ambient temperature		-65	+150	°C

## Note

## THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	note 1	150	K/W

## Note

1. Transistor mounted on an FR4 printed-circuit board.

<sup>1.</sup> Transistor mounted on an FR4 printed-circuit board.

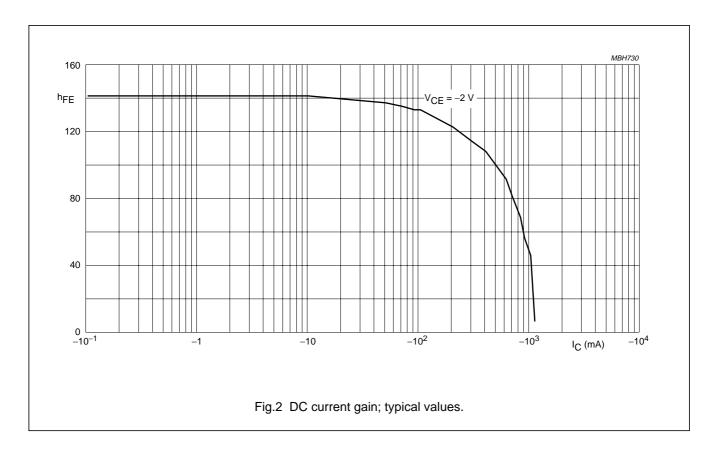
# PNP medium power transistors

BC636; BC638; BC640

# **CHARACTERISTICS**

 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I <sub>CBO</sub>	collector-base cut-off current	$V_{CB} = -30 \text{ V}; I_E = 0 \text{ A}$	_	-100	nA
		$V_{CB} = -30 \text{ V}; I_E = 0 \text{ A}; T_j = 150 ^{\circ}\text{C}$	_	-10	μΑ
I <sub>EBO</sub>	emitter-base cut-off current	$V_{EB} = -5 \text{ V}; I_C = 0 \text{ A}$	_	-100	nA
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = -2 V; see Fig.2			
		$I_C = -5 \text{ mA}$	63	_	
		$I_{\rm C} = -150 \text{ mA}$	63	250	
		I <sub>C</sub> = -500 mA	40	_	
	DC current gain	$V_{CE} = -2 \text{ V; } I_{C} = -150 \text{ mA; see Fig.2}$			
	BC636-10		63	160	
	BC636-16; BC638-16; BC640-16		100	250	
V <sub>CEsat</sub>	collector-emitter saturation voltage	$I_C = -500 \text{ mA}; I_B = -50 \text{ mA}$	_	-0.5	V
V <sub>BE</sub>	base-emitter voltage	$V_{CE} = -2 \text{ V}; I_{C} = -500 \text{ mA}$	_	-1	V
f <sub>T</sub>	transition frequency	$V_{CE} = -5 \text{ V}; I_{C} = -50 \text{ mA}; f = 100 \text{ MHz}$	100	_	MHz
h <sub>FE1</sub> h <sub>FE2</sub>	DC current gain ratio of the complementary pairs	$ V_{CE}  = 2 \text{ V};  I_C  = 150 \text{ mA}$	_	1.6	



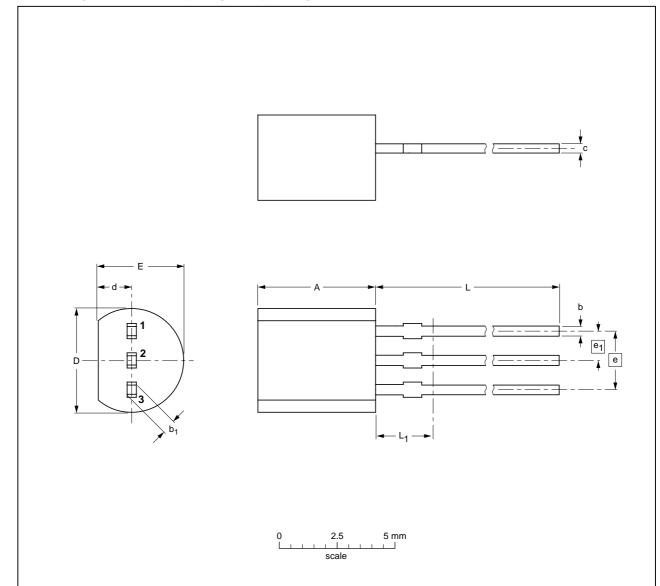
# PNP medium power transistors

BC636; BC638; BC640

# **PACKAGE OUTLINE**

# Plastic single-ended leaded (through hole) package; 3 leads

SOT54



## **DIMENSIONS (mm are the original dimensions)**

UNIT	A	b	b <sub>1</sub>	С	D	d	E	е	e <sub>1</sub>	L	L <sub>1</sub> <sup>(1)</sup> max.
mm	5.2 5.0	0.48 0.40	0.66 0.55	0.45 0.38	4.8 4.4	1.7 1.4	4.2 3.6	2.54	1.27	14.5 12.7	2.5

#### Note

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE
VERSION	ION IEC JEDEC JEITA		PROJECTION	ISSUE DATE	
SOT54		TO-92	SC-43A		<del>97-02-28</del> 04-06-28

# PNP medium power transistors

BC636; BC638; BC640

#### **DATA SHEET STATUS**

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS(2)(3)	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
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#### **DEFINITIONS**

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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Printed in The Netherlands

R75/05/pp7

Date of release: 2004 Oct 11

Document order number: 9397 750 13575

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